Sensor devices Magnetic sensors











Outline



• 5 Magnetic Sensors

Introduction

•Theory

•Galvanomagnetic Effects

•Applications



Introduction



- A magnetic sensor is a transducer that converts a magnetic field into an electrical signal
- Galvanomagnetic effects occur when a material carrying an electrical current is exposed to a magnetic field
- Hall effects, An electric field are generated when a perpendicular magnetic field plus a feeding current in a semiconductor (The effect are small in metal)
- Lorentz deflection, A current vector are generated caused by a perpendicular magnetic field
- Magnetoresistance, a modulation of the resistance by a magnetic field
- Magnetoconcentration, produce a gradient of carrier perpendicular to the magnetic field and the original current





Lorentz Force (electric field and magnetic field)



$$F = q(E + v \times B)$$

B magnetic induction vector

q charge of a carrier

V is the electron velocity (vector)*F* the force acting on the electron (vector)

X vector product

$$\boldsymbol{B} = \mu \mu_0 \boldsymbol{H}$$

 u_o is the permeability of free space u is the relative permeability







- μ>>1
- ferro or ferrimagnetic materials
 - NiFe
- μ~**1**
- Dia- or paramagnetic materals
 - Galvanomagnetic effects in semiconductor





• Drift-diffusion approximations (semiconductor)







Introduce Lorentz force in the drift diffusion approximation

$$J_n(0) = \sigma_n \mathscr{E} + q D_n \nabla n,$$

$$E \longrightarrow E + v \times B$$

$$J_n(B) = q\mu_n nE + qD_n \nabla n + qu_n nv_n \times B$$







replace

$$J_n(B) = q\mu_n nE + qD_n \nabla n - u_n J_n(B) \times B$$

Result in

$$J_n(B) = J_n(0) - u_n J_n(B) \times B$$





Solving with respect to $J_n(B)$

$$\boldsymbol{J}_n(\boldsymbol{B}) \approx [\boldsymbol{J}_n(0) + \mu_n \boldsymbol{B} \times \boldsymbol{J}_n(0) + (\mu_n)^2 \boldsymbol{B} \cdot \boldsymbol{J}_n(0) \boldsymbol{B}] [1 + (\mu_n \boldsymbol{B})^2]^{-1}$$

Both cross product and scalar product

Scattering mechanism

< > Means

average

$$r_n = \langle \tau^2 \rangle / \langle \tau \rangle^2$$

Low doped silicon r_n~1.15





$$\mu_n^* = r_n \mu_n.$$

Adjusting the mobility with respect to scattering factors

$$J_n(B) = [J_n(0) + \mu_n^* B \times J_n(0) + K(\mu_n^*)^2 B \cdot J_n(0) B] [1 + (\mu_n^* B)^2]^{-1}.$$





Semiconductor sample without concentration gradients

$$\boldsymbol{J}_n(\boldsymbol{B}) = \sigma_{nB} [\mathscr{E} + \mu_n^* \boldsymbol{B} \times \mathscr{E} + K(\mu_n^*)^2 (\boldsymbol{B} \cdot \mathscr{E}) \boldsymbol{B}]$$

$$\sigma_{nB} = \sigma_n [1 + (\mu_n^* B)^2]^{-1}.$$

Magnetic field dependent conductivity

If magnetic field **B** is parallel to **E** then

Which is the longitudinal magneto resistance effect.

$$\overline{J}_n(B) = \sigma_{nB} \Big[1 + K(\mu_n^* B)^2 \Big] \overline{E}$$





B is perpendicular to **E**, scalar product is therefore zero. The diffusion is also assumed to be negligible, then

$$\boldsymbol{J}_n(\boldsymbol{B}) = \sigma_{nB}(\mathscr{E} + \mu_n^* \boldsymbol{B} \times \mathscr{E}).$$

The Electric field and the current density is assumed to be in the x-y plane. Result in;

$$J_{nx} = \sigma_{nB}(\mathscr{E}_x - \mu_n^* B \mathscr{E}_y) \qquad J_{ny} = \sigma_{nB}(\mathscr{E}_y + \mu_n^* B \mathscr{E}_x).$$



Theory, Hall Effect



In the case of a long (in x-direction) sample, then the $J_{ny}=0$ The Hall field is then:



ohmic contacts. Equipotential lines are deflected from vertical direction by Hall angle θ_{H} . The Hall voltage appears between border locations 1 and 2. The curves originate from numerical modeling with $\mu_{n}^{*}B = 0.21$. (After Ref. 3)





Theory, Lorentz deflection



In the case of a short sample, Hall field is zero and $E_v=0$



A lateral current component is present, the current is therefore deflected

$$-J_{ny}/J_{nx} = \mu_n^* B = \tan \theta_L.$$

Current imbalance caused by the deflection

$$I_L = \mu_n^* (L/W) IB,$$

The semiconductor must have a high mobility for high sensitivity, InSb and InAs are good candidates



Theory, Magnetoconcentration



Current crowding because of local increase in conductivity Important in devices like magnetodiodes and magnetotransistors

Fig. 6 Magnetoconcentration in a nearly intrinsic (T = 500 K) bulk silicon plate. Current lines connect ohmic contacts and crowd near bottom. Equipotential lines are approximately parallel to the contacts. The curves originate from modeling with $\mu_n^*B = 0.21$ and $\mu_p^*B = 0.07$. (After Ref. 3)















Theory, magnetoresistive, typical **MIUN.SE** signal output





Theory, magnetoresistive, Read out circuit





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Applications



	Hall	MR
Process Technology	Silicon IC	NiFe Thin Film
Sensitivity	10uv/v/g	2 mv/v/g
Saturation Field	None	10 - 100g
Linearity	< 1%	$\cos^2 \Theta$
Sensitive Axis	Perpendicular to	Parallel to
	plane of chip	plane of chip
Output for Constant Field	Yes	Yes

Hall Effect Sensor Magnetoresistive Sensor Ν



Giant magnetoresistivity







Giant Magnetoresistivity Basics

Sandwich structures combining ferromagnetic and diamagnetic metallic thin films

Giant Magnetoresistive Effect (GMR)

- Significant change in the electrical resistance (10 15%) when the structure is subjected to the external magnetic field.
- Caused by spin dependent scattering of electrons in thin film sandwich structure.
- External magnetic field changes the magnetic orientation of the ferromagnetic layers and thus affects the flow of electrons.





The mobility of electrons with the parallel spin is higher than those with anti-parallel spin.





Application Comparison







Applications, integrated bulk hall MIUN.SE devices









Applications, Hall MAGFET



The channel is used as a extremely thin hall plate. High 1/f noise







Applications, Vertical Magneto transistors

Lorentz deflection

Sensitivity similar as for dual-drain MAGFET







Applications, Magnetodiodes



- Magnetoconcentration
- Use of a high and a low recombination surface S1 respectively S2

The current change in the device caused by the deflection towards low recombination or high recombination surfaces





Exercise



1)

An Si plate is doped with phosphorus and boron. $N_D = 4 \times 10^{14} \text{ cm}^{-3}$, $N_A = 4.001 \times 10^{14} \text{ cm}^{-3}$, $r_n = 1.15$, $r_p = 0.7$, $\mu_p = 0.047 \text{ T}^{-1}$, $\mu_n = 0.138 \text{ T}^{-1}$. What is the value for R_H ?

2)

A Hall plate is integrated using a standard bipolar IC process (Fig. 11). The epi layer defining the plate has a thickness of 10 μ m and a sheet resistance $\rho_s = 1000 \Omega/\text{sq}$. Assume $L = 600 \mu$ m, and $W = 200 \mu$ m. The supply current is I = 10 mA and the presence of a magnetic induction B = 100 Gauss. Calculate:

- a) the Hall coefficient, R_H
- b) the Hall voltage, V_H
- c) the Hall angle, θ_H
- d) the supply-voltage related sensitivity, S_V .



Exercise



3) Hall structure ,V_L=0.1 V, Bz=10*E-5 Wb/cm2, Vsc₁₂=

-2mV, t=10um, L=5mm, w=0.1 mm, I=1 mA, find the type, concentration, and mobility of the majority carrier. answer; electrons, $3.125E17 \text{ cm}^{-3}$, $u_n = 10000 \text{ cm}^2(\text{Vs})^{-1}$





